

09/473305

ABSTRACT OF DISCLOSURE

- A surface mount-type microelectronic component assembly which does not physically attach the microelectronic component to its carrier substrate. Electrical contact is achieved between the microelectronic component and the carrier with solder
- 5 balls attached to either the microelectronic component or the carrier substrate. A force is exerted on the assembly to achieve sufficient electrical contact between the microelectronic component and the carrier substrate.

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